



## MOSFETs Silicon 40V N-Channel MOS

**■ Applications**

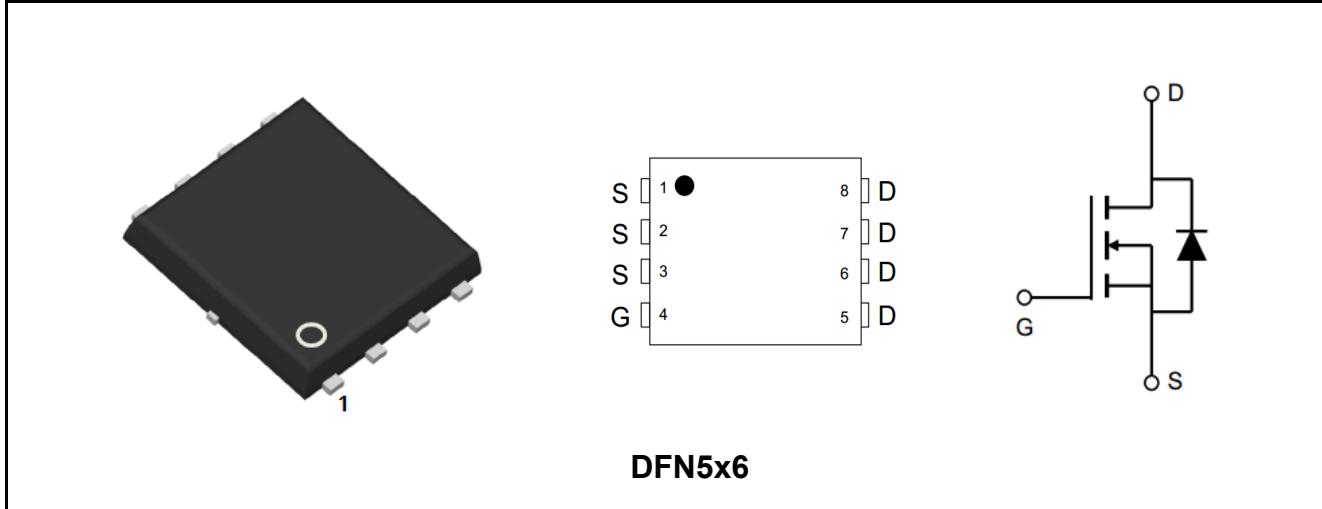
- Synchronous Rectification
- Industrial and Motor Drive
- DC/DC and AC/DC Converters
- Power Tools

**■ Features**

- High-Speed Switching
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Enhanced Avalanche Ruggedness
- RoHS and Halogen-Free Compliant
- 100% UIS and RG Tested

**■ Product Summary**

$V_{DS}$	40	V
$I_D$	110	A
$R_{DS(ON)} \text{ ,Typ@10V}$	3.4	$\text{m}\Omega$
$Q_g$	21	nC



Marking	Package	Packaging	Min. package quantity
MDG004R040SH	DFN5x6	Tape & Reel	5000



**■ Absolute Maximum Ratings (Tc=25°C unless otherwise noted)**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DS</sub>	40	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current Tc=25°C (Note 1)	I <sub>D</sub>	110	A
Continuous Drain Current Tc=100°C (Note 1)		70	A
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	300	A
Total Dissipation	P <sub>D</sub>	83	W
Junction Temperature	T <sub>j</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55-150	°C
Single Pulse Avalanche Energy (Note 2)	E <sub>AS</sub>	220	mJ

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

**■ Thermal Characteristics**

Parameter	Symbol	Max	Unit
Maximum Junction-to-Case	R <sub>θJC</sub>	1.5	°C/W
Maximum Junction-to-Ambient (Note 3)	R <sub>θJA</sub>	50	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V<sub>DD</sub>=50V, T<sub>ch</sub>= 25°C(initial), L=0.5mH, R<sub>g</sub>=25Ω.

Note 3: The value of R<sub>θJA</sub> is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25° C. The value in any given application depends on the user's specific board design.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



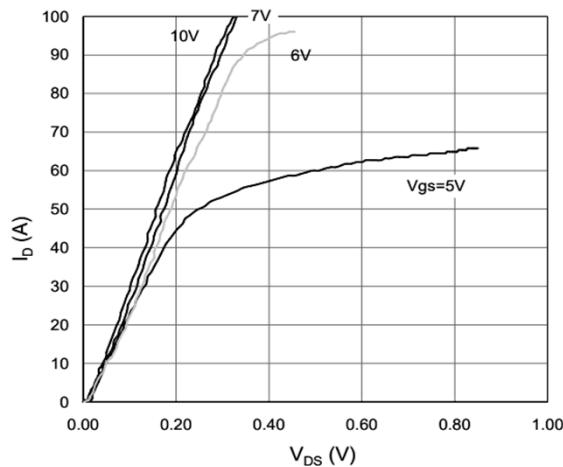
■ Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	40	-	-	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V	-	-	1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2	2.7	3.5	V
Drain-Source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	3.4	4	mΩ
		T <sub>j</sub> =125°C	-	5.2	-	
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, f=1.0MHz	-	1400	-	pF
Output Capacitance	C <sub>oss</sub>		-	477	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	44	-	pF
Gate Resistance	R <sub>g</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1.0MHz	-	2.06	-	Ω
<b>Switching Parameters</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =20V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V, R <sub>L</sub> =2Ω	-	15	-	ns
Turn-On Rise Time	t <sub>r</sub>		-	40	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>		-	18	-	ns
Turn-Off Fall Time	t <sub>f</sub>		-	10	-	ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =20V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	21	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	5.9	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	4.8	-	nC
<b>Source-Drain Characteristics</b>						
Diode Forward Voltage	V <sub>sd</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =10A	-	0.78	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> =20V, I <sub>F</sub> =20A, di/dt=100A/us	-	38	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	30	-	nC

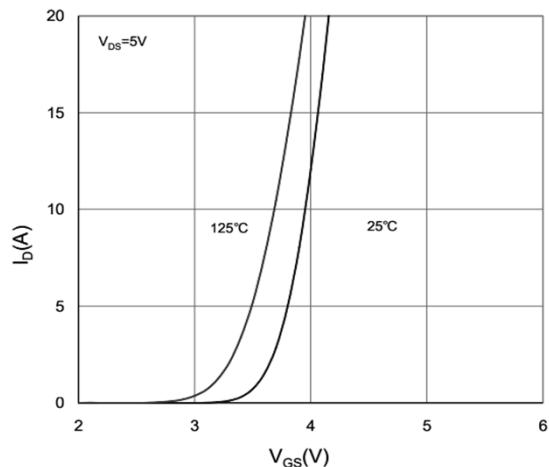




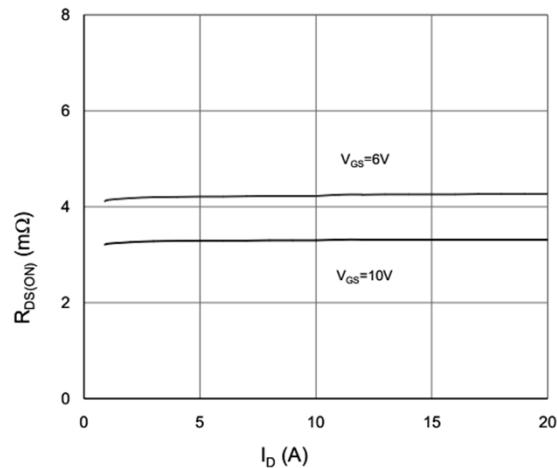
## ■ Characteristics Curves



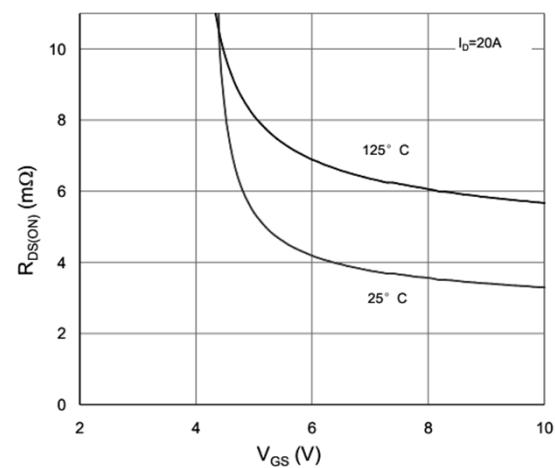
Output Characteristics



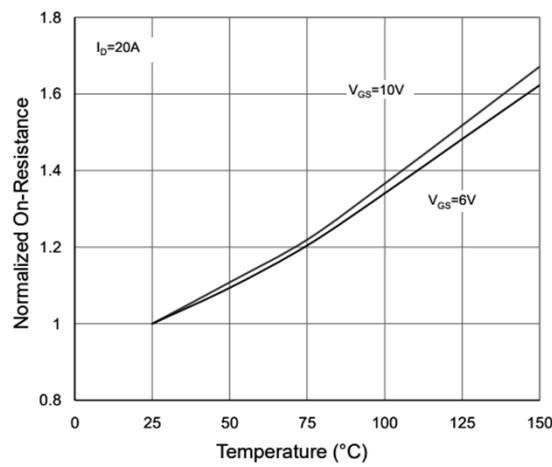
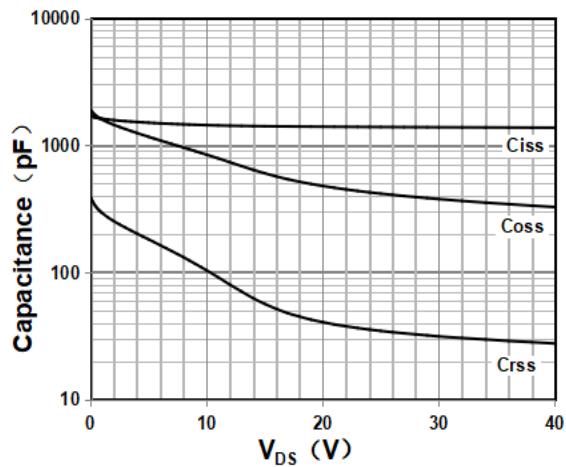
Transfer Characteristics



On Resistance Vs Drain Current

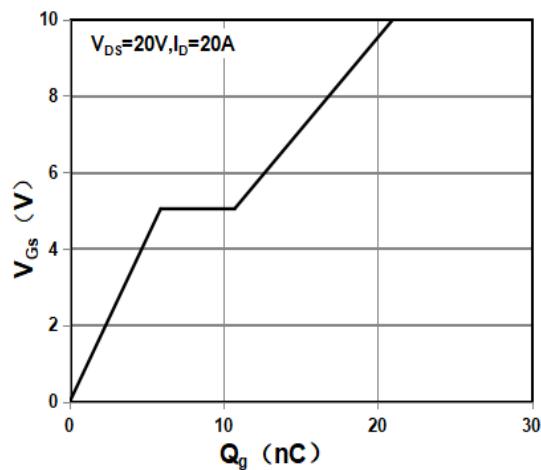


On Resistance Vs Gate Source Voltage

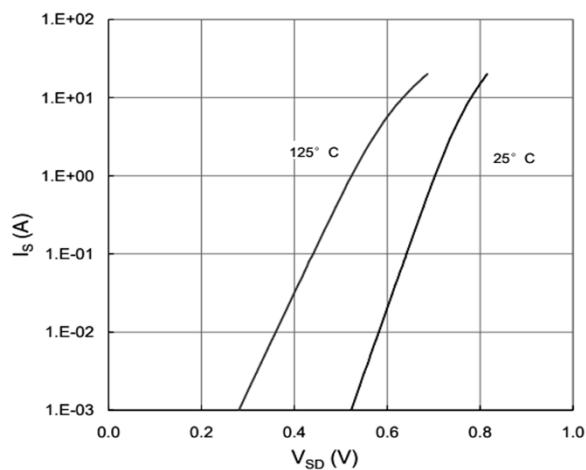
R<sub>dson</sub>-JunctionTemperature

Capacitance

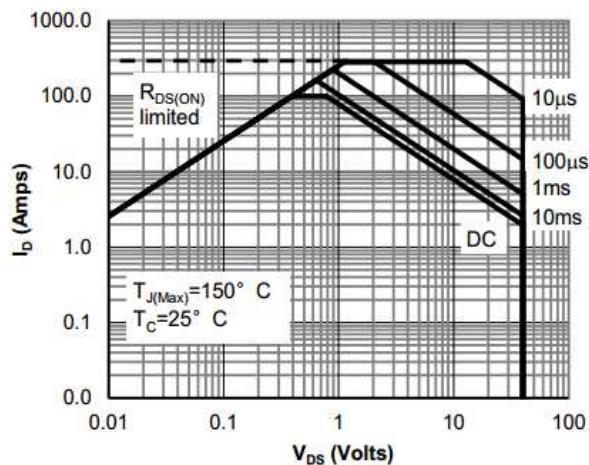




Gate Charge Waveform



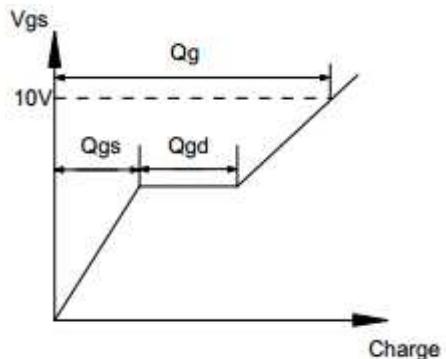
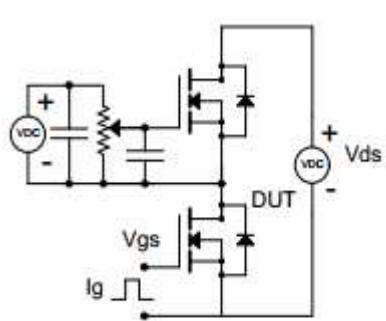
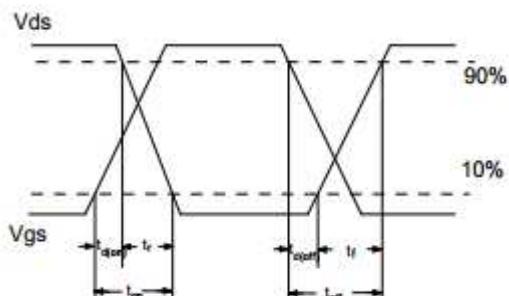
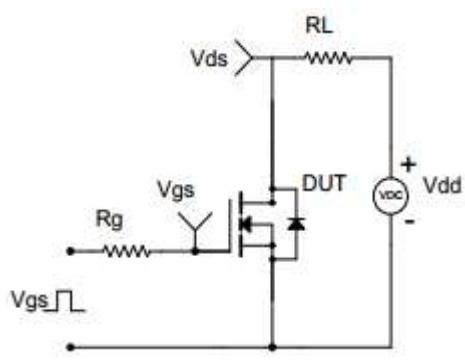
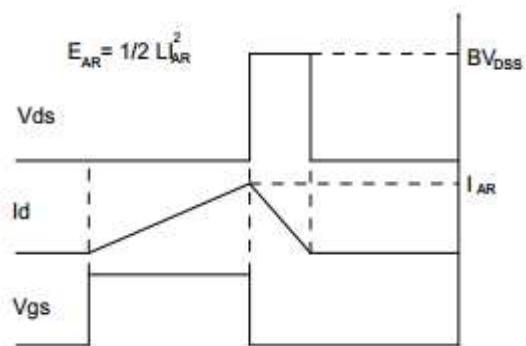
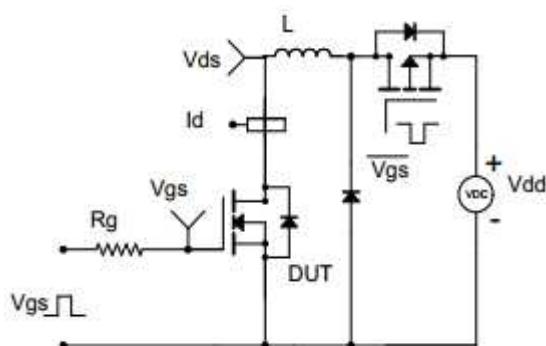
Source-Drain Diode Forward Voltage



Maximum Safe Operating Area

Note : The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



**■ Test Circuit & Waveform****Gate Charge Test Circuit & Waveform****Resistive Switching Test Circuit & Waveform****Unclamped Inductive Switching (UIS) Test Circuit & Waveform**

**■ DFN5x6 Package Dimensions**

Unit: mm

Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
A	0.90		1.10	k	1.15		1.35
A3	0.15		0.30	b	0.20		0.40
D	5.05		5.25	e	1.15		1.35
D1	4		4.2	L	0.50		0.65
D2	4.75		5.05	L1	0.43		0.55
E	5.85		6.15	H	0.55		0.68
E1	3.35		3.55	$\theta$	8°		12°
E2	5.55		5.85				

